

2SD1391

Silicon NPN Triple-Diffused Junction Mesa Type

Horizontal Deflection Output

■ Features

- High breakdown voltage and high reliability by glass passivation
- High speed switching
- Wide area of safety operation (ASO)

■ Absolute Maximum Ratings (Tc=25°C)

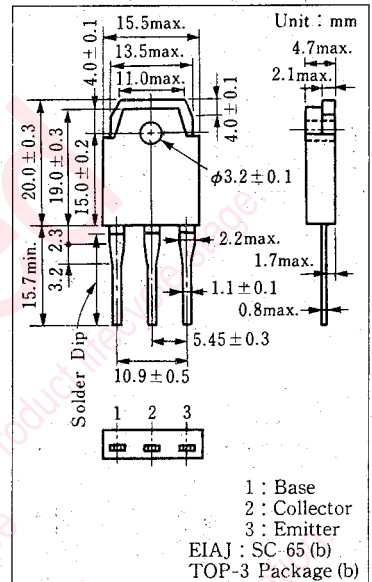
Item	Symbol	Value	Unit
Collector-base voltage	V _{CB0}	1500	V
Collector-emitter voltage	V _{CES}	1500	V
	V _{CEO}	700	V
Emitter-base voltage	V _{EBO}	6	V
Collector current	I _C	5	A
Peak collector current	I _{CP} *	17	A
Peak base current	I _{BP}	3.5	A
Reverse peak base current	I _{BP}	-2.5	A
Collector power dissipation	T _c =25°C	100	W
	T _a =25°C	2.5	
Junction temperature	T _j	150	°C
Storage temperature	T _{stg}	-55~150	°C

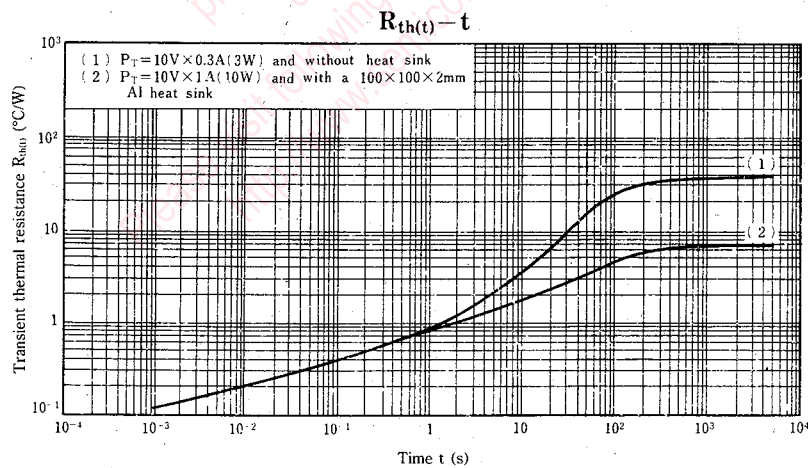
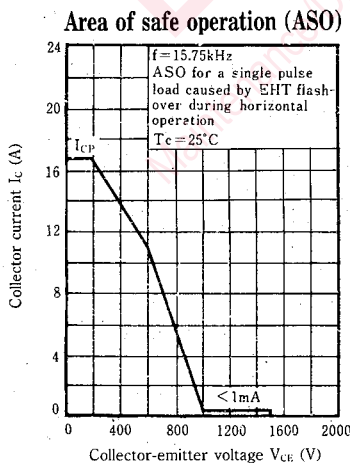
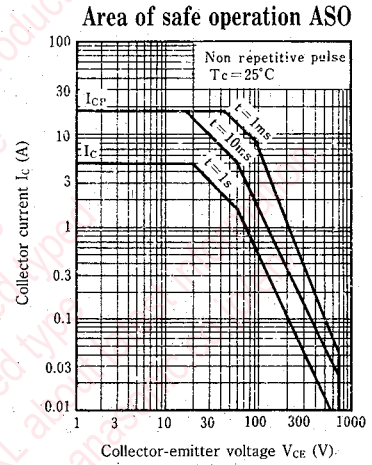
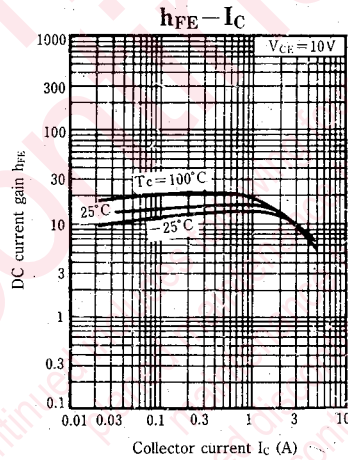
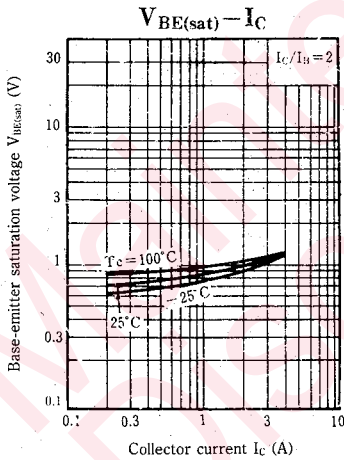
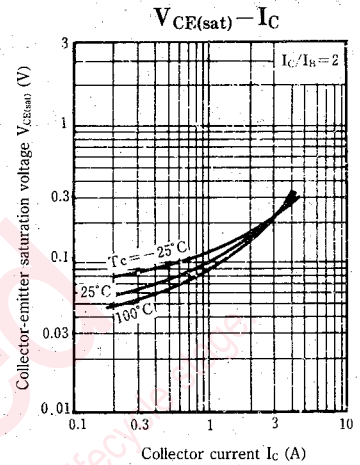
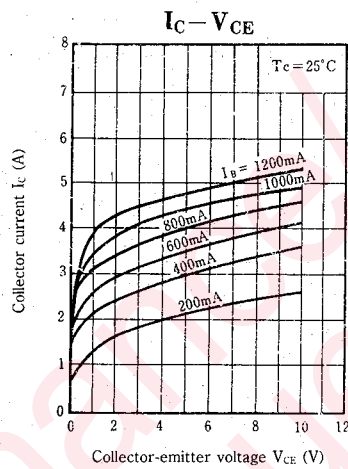
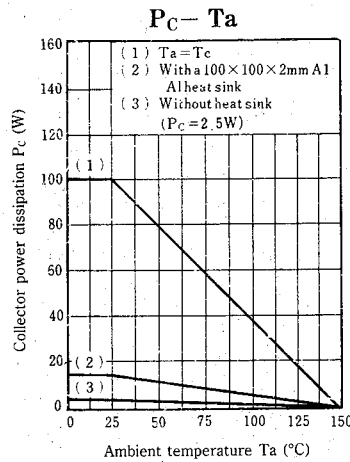
* Non repetitive peak value

■ Electrical Characteristics (Tc=25°C)

Item	Symbol	Condition	min.	typ.	max.	Unit
Collector cutoff current	I _{CBO}	V _{CB} =750 V, I _E =0			50	μA
		V _{CB} =1500 V, I _E =0			1.0	mA
Emitter-base voltage	V _{EBO}	I _E =1 mA, I _C =0	6			V
DC current gain	h _{FE}	V _{CE} =10V, I _C =4A	4		15	
Collector-emitter saturation voltage	V _{CE(sat)}	I _C =4.5 A, I _B =2 A			2.0	V
Base-emitter saturation voltage	V _{BE(sat)}	I _C =4.5 A, I _B =2 A			1.3	V
Transition frequency	f _T	V _{CE} =10V, I _C =0.5A, f=0.5MHz		2		MHz
Fall time	t _f	I _C =4 A, I _{Bend} =1.5 A			1.0	μs
Storage time	t _{stg}	L _B =10 μH			11	μs

■ Package Dimensions





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